

	Type	Hits	Search Text	DBs
1	IS&R	34	((("6077784") or ("5789320") or ("6008120") or ("5494854") or ("5913712") or ("5328553") or ("5658806") or ("6187683") or ("5851603") or ("6114209") or ("6117345") or ("6077784") or ("5798283") or ("5798299") or ("5942801") or ("5960295") or ("5963788") or ("6191028")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	IS&R	16	((("5789320") or ("6008120") or ("5494854") or ("5328553") or ("5658806") or ("5851603") or ("5798283") or ("5798299")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	42484	(chemical adj mechanical adj polishing) or CMP	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	776	((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) same (dielectric adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	633	((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	234	((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	5	((((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)) and (polish\$4 with (dielectric adj layer) with (planar adj surface)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	0	(((((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)) and (polish\$4 with (dielectric adj layer) with (planar adj surface)))) and (dielectric adj cap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	4	(((((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)) and (polish\$4 with (dielectric adj layer) with (planar adj surface)))) and polysilicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	IS&R	L1	2	("5494854").PN.	USPAT; US-PGPUB; ; EPO; JPO; DER WENT; IBM_T DB	2004/02/12 15:48	
2	BRS	L3	3	((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)) and (dielectric adj cap)	USPAT; US-PGPUB; ; EPO; JPO; DER WENT; IBM_T DB	2004/02/12 15:50	
3	BRS	L2	3	((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)) and (dielectric adj cap)	USPAT; US-PGPUB; ; EPO; JPO; DER WENT; IBM_T DB	2004/02/12 15:50	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	470	438/637.ccls. and (cap\$6 or scratch\$4 or indent\$4) and ((chemical adj mechanical adj polishing) or CMP) and dielectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 12:30	
2	BRS	L2	57	438/637.ccls. and (cap\$6 or scratch\$4 or indent\$4) and ((chemical adj mechanical adj polishing) or CMP) and (dielectric with polish\$4) and (first adj conduct\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 13:30	
3	BRS	L3	294	1 and (conduct\$4 with dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 13:30	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
4	BRS	L4	99	438/637.ccls. and (cap\$6 or scratch\$4 or indent\$4) and ((chemical adj mechanical adj polishing) or CMP) and ((dielectric with polish\$4) same (conduct\$4 with dielectric))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 13:31	
5	BRS	L5	151	438/637.ccls. and ((chemical adj mechanical adj polishing) or CMP) and ((dielectric with polish\$4) same (conduct\$4 with dielectric))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 13:35	
6	BRS	L6	93	5 and cap\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 13:39	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
7	BRS	L7	93	5 and (cap\$6 or \$4cap)	USPAT; US-P GPUB ; EPO; JPO; DER WEN T; IBM_T DB	2004/03/22 13:40	

	Type	Hits	Search Text	DBs
1	IS&R	34	(("6077784") or ("5789320") or ("6008120") or ("5494854") or ("5913712") or ("5328553") or ("5658806") or ("6187683") or ("5851603") or ("6114209") or ("6117345") or ("6077784") or ("5798283") or ("5798299") or ("5942801") or ("5960295") or ("5963788") or ("6191028")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	IS&R	16	(("5789320") or ("6008120") or ("5494854") or ("5328553") or ("5658806") or ("5851603") or ("5798283") or ("5798299")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	42484	(chemical adj mechanical adj polishing) or CMP	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	776	((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) same (dielectric adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	633	((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	234	((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	5	((((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)) and (polish\$4 with (dielectric adj layer) with (planar adj surface)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	0	(((((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate))) and (polish\$4 with (dielectric adj layer) with (planar adj surface)))) and (dielectric adj cap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	4	(((((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate))) and (polish\$4 with (dielectric adj layer) with (planar adj surface)))) and polysilicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Time Stamp	Comments	Error Definition	Errors
1	2004/02/11 17:41			0
2	2004/02/12 15:48			0
3	2004/02/12 11:25			0
4	2004/02/12 11:26			0
5	2004/02/12 11:27			0
6	2004/02/13 13:54			0
7	2004/02/12 12:50			0
8	2004/02/12 11:49			0
9	2004/02/12 12:50			0

	Type	Hits	Search Text	DBs
10	IS&R	2	("5494854").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
11	BRS	3	((((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)) and (dielectric adj cap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	BRS	3	((((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)) and (dielectric adj cap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	IS&R	2	("5,494,854").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14	BRS	234	((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15	BRS	15	((((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)) and ((dielectric adj layer) with (HDPCVD or (high adj density adj plasma adj chemical adj vapor adj	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
16	BRS	7	(((((chemical adj mechanical adj polishing) or CMP) and ((first adj conduct\$4 adj layer) with (dielectric adj layer) with substrate)) and ((dielectric adj layer) with (HDPCVD or (high adj density adj plasma adj chemical adj vapor adj deposition)))) and ((dielectric adj layer) with (PECVD or (plasma adj enhanced adj chemical adj vapor adj deposition))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB



	Time Stamp	Comments	Error Definition	Errors
10	2004/02/12 15:48			0
11	2004/02/12 15:50			0
12	2004/02/12 15:50			0
13	2004/02/12 18:19			0
14	2004/02/13 15:02			0
15	2004/02/13 13:58			0
16	2004/02/13 13:59			0